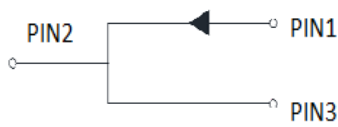
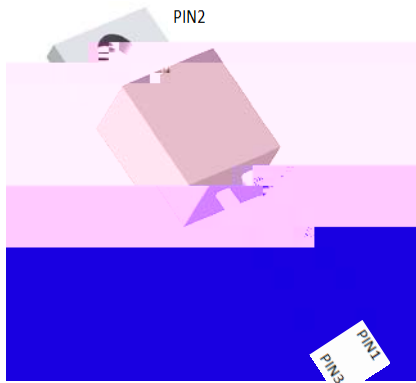


Ultra-Fast Recovery Diodes 8A FRED



Features

- Adopt FRED chip
- Low forward Voltage drop
- Fast reverse recovery time
- High frequency operation
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- Guard ring for enhanced ruggedness and long life
- Temperature range: -55°C to +175°C
- Leadless, solderable per MIL-STD-883C, Method 2002 and JESD22-B102
- Polarity:** As marked

Maximum Ratings (T_j=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	MUR860L
Device marking code			MUR860L c(FIG.1)

Surge(Non-repetitive)Forward Current @60Hz half sine-wave, 1 cycle, T _j =25	I _{FSM}	A	50
Current Squared Time @1ms t 8.3ms T _j =25	I ² t	A ² s	12.5
Storage Temperature	T _{stg}		-55 ~ +175
Junction Temperature	T _j		-55 ~ +175
Typical Junction capacitance @4V,1MHz	C _j	pF	42



MUR860L

Electrical Characteristics

PARAMETER	SYMBOL	UNIT	TEST CONDITIONS	Min	Typ	Max
Instantaneous forward voltage drop per diode	V_{FM}	V	IFM=8.0A @Tj=25	-	2.15	3.0
			IFM=8.0A @Tj=150	-	-	2.0
DC reverse current at rated DC blocking voltage per diode	I_{RRM1}	uA	VRM=VRRM Tj=25	-	-	5.0
	I_{RRM2}		VRM=VRRM Tj=150	-	25	200
Reverse Recovery Time	Trr	ns	IF=0.5A IRM=1A IRR=0.25A Tj=25	-	17	25
			Tj=25	-	40	-
			Tj=125	-	95	-
Peak recovery current	I_{RRM}	A	Tj=25	-	1.9	-
			Tj=125	-	3.8	-
Reverse recovery charge	Qrr	nC	Tj=25	-	40	-
			Tj=125	-	185	-

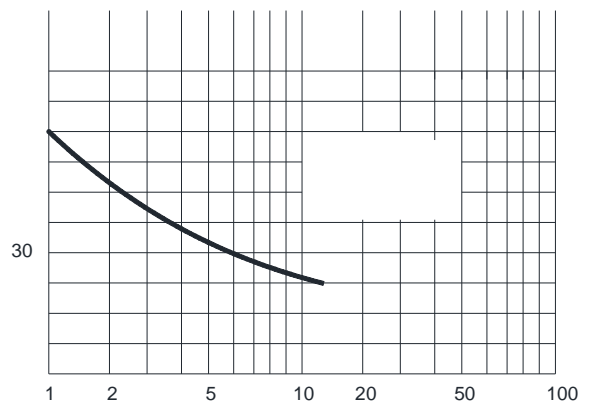
Thermal Characteristics Tj=25 Unless otherwise specified

PARAMETER		SYMBOL	UNIT	MUR860L
Thermal Resistance	Between junction and case	R J-C	/W	2.0
Thermal Resistance	Between junction and Air	R J-A	/W	50

Ordering Information (Example)

PREFERRED P/N	UNIT WEIGHT(g)	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
MUR860L	Approximate 1.8	50	1000	5000	Tube

Characteristics (Typical)





MUR860L

Disclaimer

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The product listed herein is designed to be used with ordinary electronic equipment or devices, and not designed to be used with equipment or devices which require high level of reliability and the malfunction of which would directly endanger human life (such as medical instruments, transportation equipment, aerospace machinery, nuclear-reactor controller